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BUMP ELECTRODE BOND-FORMATION METHOD

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[There are no amendments to this patent.]

Claim

Bump electrode bond formation method characterized in that it includes the fact that, in a bump electrode bond formation method wherein multiple bump electrodes are provided on the surfaces of each of a pair of semiconductor chips and the aforementioned bumps corresponding to them are bonded facing each other, a second bump electrode, with a diameter smaller than that of a first bump electrode, made of a hard metal coated with a soft metal, is bonded so as to intrude into the aforementioned first bump electrode that consists of the aforementioned soft metal.

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